

BRMAC97A6MC

Rev.D Nov.-2015

描述 / Descriptions

SOT23-3 塑封封装双向可控硅。 Triac in a SOT23-3 Plastic Package.

特征 / Features

四种灵敏的门触发模式适合于各种组合的触发电源。

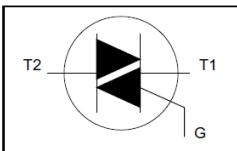
Sensitive Gate Triggering in Four Trigger Modes for all possible Combinations of Trigger Sources..

用途 / Applications

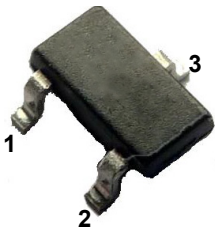
用于固态继电器、微处理器面板、TTL 逻辑门、工业灯具。

Used in solid state relays. MPU interface. TTL logic and any other industrial application.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1 : T1

PIN 2 : T2

PIN 3 : G

放大及印章代码 / h_{FE} Classifications & Marking

见印章说明。 See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Repetitive peak off-state voltages	V_{DRM}	400	V
RMS on-state current	$I_{T(RMS)}$	0.6	A
Non-repetitive peak on-state current	$I_{TSM}(t=20ms)$	8.0	A
Non-repetitive peak on-state current	$I_{TSM}(t=16.7ms)$	8.8	A
I^2t for fusing	$I^2t_{(t=10ms)}$	0.32	A ² S
Repetitive rate of rise of on-state current after triggering $I_{TM}=1A, I_G=0.2A,$ $dI_G/dt=0.2A/\mu s$	dI_T/dt	T2+ G+	50
		T2+ G-	50
		T2- G-	50
		T2- G+	10
Peak gate current	$I_{GM}(t=2\mu s_{max})$	1.0	A
Peak gate voltages	$V_{GM}(t=2\mu s_{max})$	5.0	V
Peak gate power	$P_{GM}(t=2\mu s_{max})$	5.0	W
Average gate power	$P_{G(AV)}$ ($T_{case}=80^\circ C, t=2\mu s_{max}$)	0.1	W
Junction Temperature	T_j	-40~125	°C
Storage Temperature Range	T_{stg}	-40~150	°C

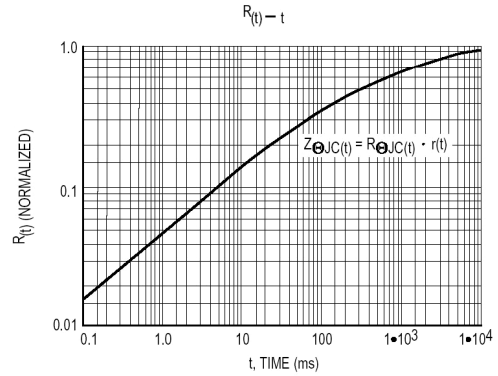
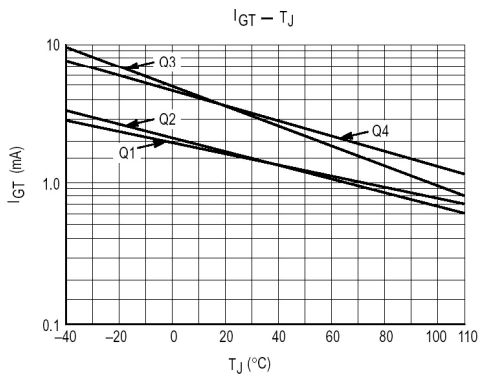
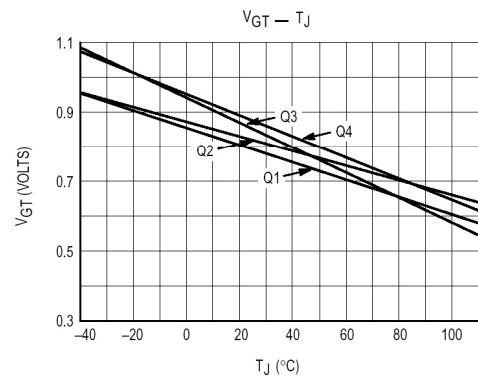
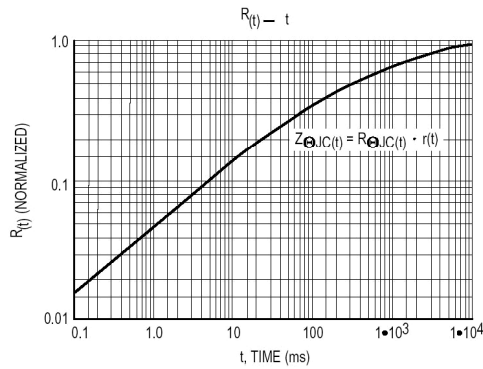
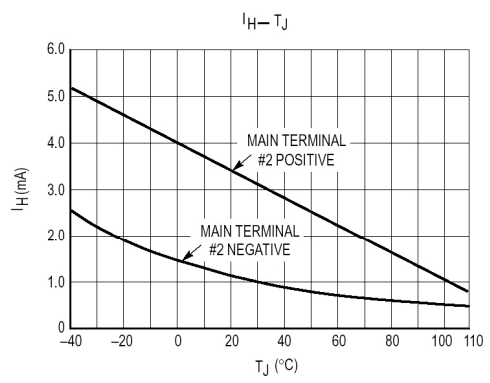
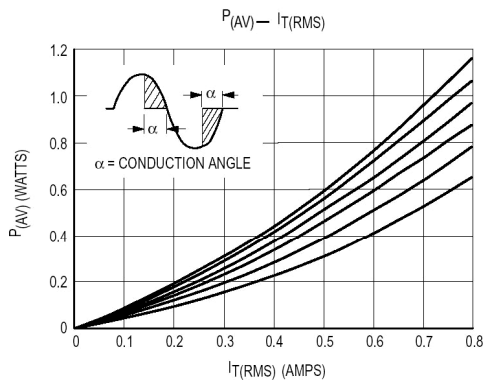
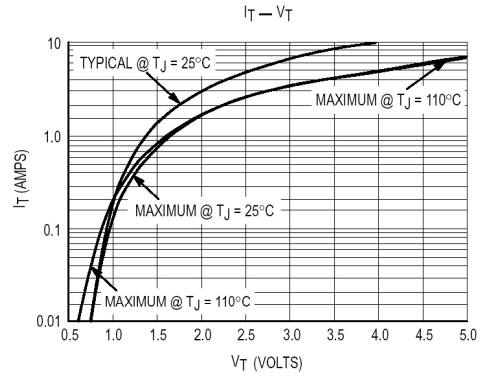
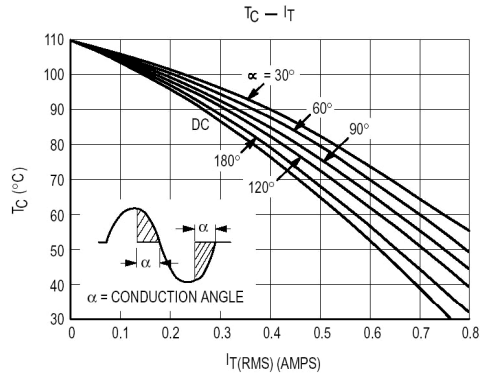
电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Gate trigger current	I_{GT}	$V_D=12V,$ $I_T=0.1A$	T2+G+	1.0	5.0	mA
			T2+G-	2.0	5.0	
			T2-G-	2.0	5.0	
			T2-G+	4.0	7.0	
Latching current	I_L	$V_D=12V;$ $I_{GT}=0.1A$	T2+G+	1.0	10	mA
			T2+G-	5.0	10	
			T2-G-	1.0	10	
			T2-G+	2.0	10	
Holding current	I_H	$V_D=12V, I_{GT}=0.1A$		1.0	10	mA
On-state voltage	V_T	$I_T=0.85A$		1.4	1.9	V

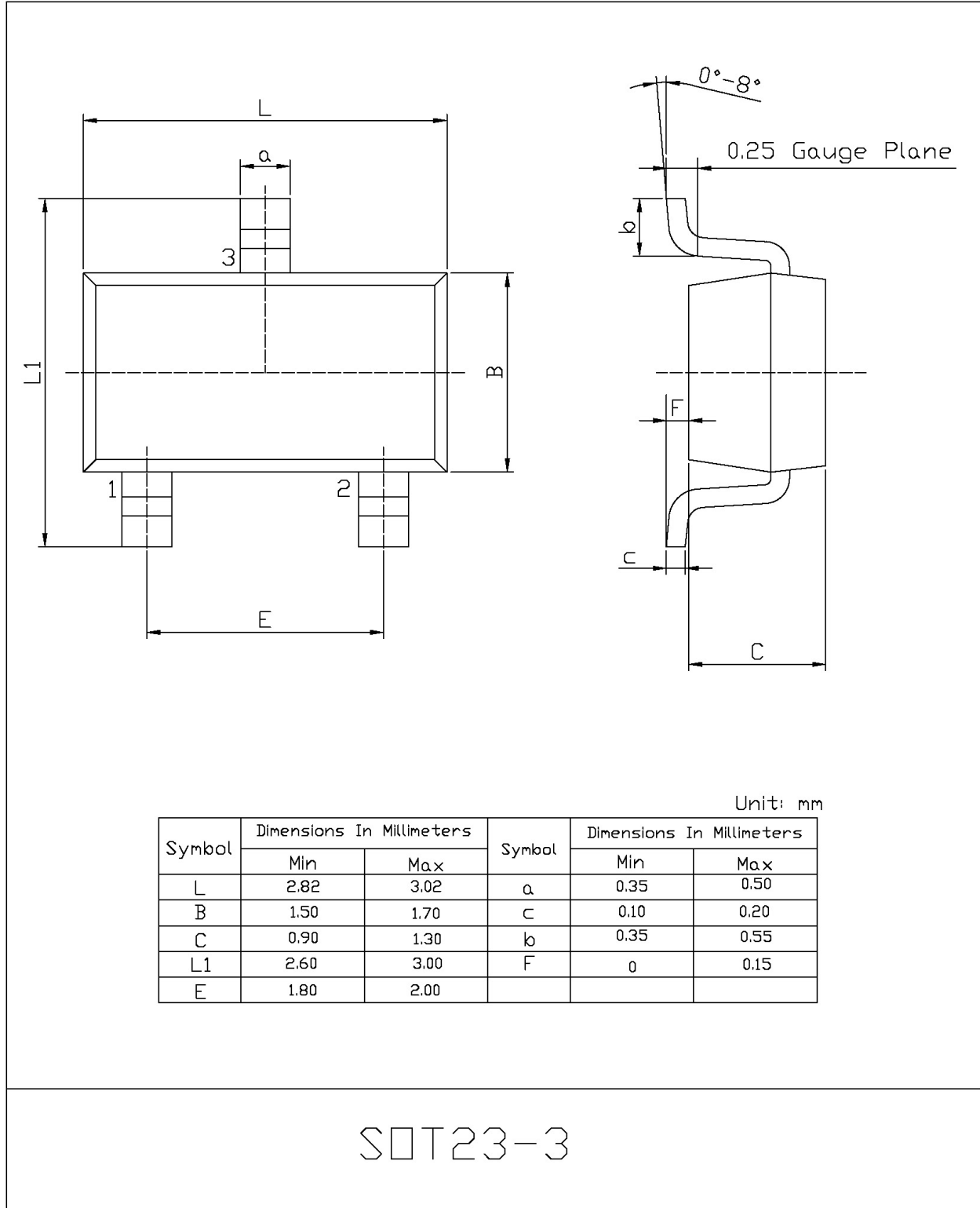
电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Gate trigger voltage	V _{GT}	V _D =12V I _T =0.1A		0.9	2.0	V
		V _D =V _{DRM} I _T =0.1A T _J =110°C	0.1	0.7		
Off-state leakage current	I _D	V _D =V _{DRM(max)} T _J =110°C		3.0	100	μA
Gate Controlled Turn-On Time	tgt	I _{TM} =1.0A V _D =V _{DRM} I _G =25mA, dI _G /dt=5A/μs		2.0		μs
Critical Rate-of-Rise of Commutation Voltage	dV _D /dt	V _D =67% of V _{DM(max)} , T _{case} =110°C exponential waveform gate open circuit	30	45		V/μs
Critical Rate-of-Rise of Off State Voltage	dV _{com} /dt	V _D =rated V _{DRM} , T _{case} =50°C I _{TM} =0.84A Commutating dI/dt=0.3A/ms		5.0		V/μs
Critical rate of rise of off-state current	I _{DRM}	V _D =Rated V _{DRM} T _J =110°C			0.1	mA
Repetitive peak off-state current	I _{RDM}	Gate Open			0.1	mA

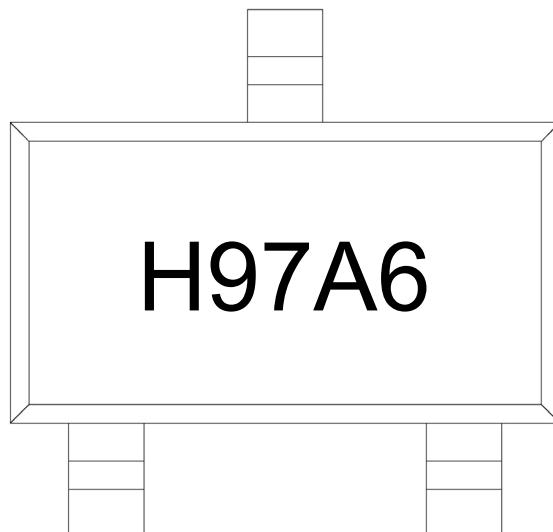
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions



印章说明 / Marking Instructions



说明：

H： 为公司代码

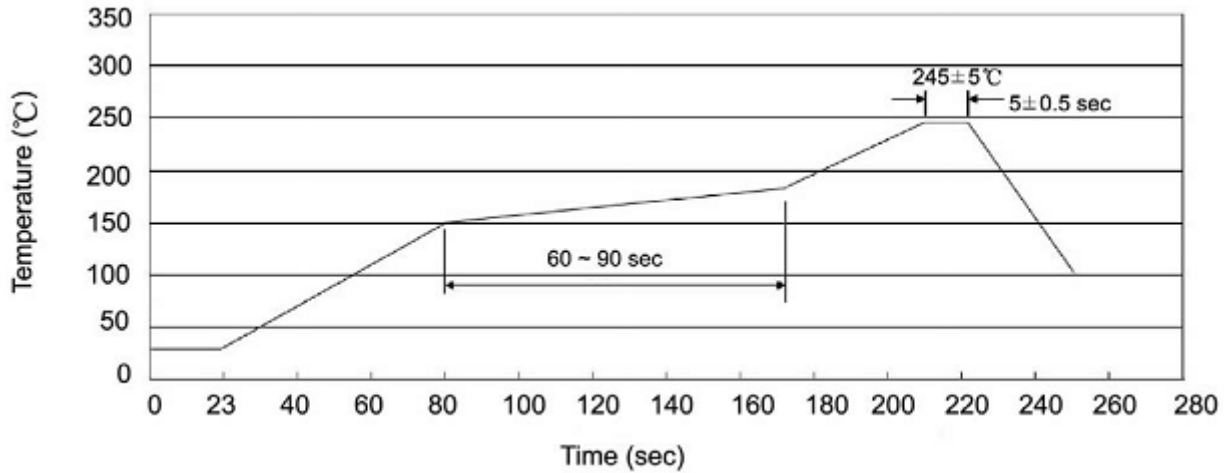
97A6： 为型号代码

Note:

H: Company Code.

97A6: Product Type.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25~150°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23-3	3,000	10	30,000	4	120,000	7" ×8	210×205×205	445×230×435

使用说明 / Notices